BONDING TOOL COOLING APPARATUS AND METHOD FOR COOLING BONDING TOOL

ABSTRACT

A bonding tool cooling apparatus (10) provided in the vicinity of a bonding stage, including a frame (12); a cooling member (16) including a ground plate (14) having a ground surface (14a) on which a front edge surface of a bonding tool (61) is grounded, and a radiation fin (15) attached to an opposite surface of the ground plate (14) to the ground surface (14a), wherein the cooling member (16) is supported on the frame (12) by a support mechanism (200) so that the cooling member (16) is rotatable about two axes, i.e., an X axis extending along the ground surface (14a) and a Y axis extending along the ground surface (14a). Bonding tool cooling time can be thereby reduced.

FIGURE 2